IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:	)	Before the Examiner
	)	
Michael T. Meyer	)	Group Art Unit
	)	
Serial No. 10/635,101	)	
	)	
Filed: August 6, 2003	)	
	)	
APPARATUS FOR HEAT TRANSFER AND CRITICAL HEAT FLUX ENHANCEMENT	)	October 6, 2003

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure embodied in 37 CFR §1.56, Applicant wishes to formally bring to the attention of the Examiner the following patents, publications and/or other information:

The references are listed on the attached Form 1449.

Copies of cited items are enclosed herewith.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 6, 2003.

Clifford W. Browning
Name of Registered Representative

Signature

October 6, 2003
Date of Signature

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No fee is believed to be due, however, should any fee be required, please charge such fee to Deposit Account No. 23-3030, but not to include any payment of issue fees.

Respectfully submitted

By: _____

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet 1 of 3

	Complete if Known
Application Number	10/635,101
Filing Date	August 6, 2003
First Named Inventor	Michael T. Meyer
Art Unit	
Examiner Name	
Attorney Docket Number	16380-4

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.[1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T[2]
		BOWERS, M.B. et al., High flux boiling in low flow rate, low pressure mini-channel and micro-channel heat sinks. Int. J. Heat Mass Transfer, Vol. 37, No. 2, pp.321-332, 1994, Great Britain.	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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		Maddox, D.E. et al., Single- and Two-Phase Convective Heat Transfer from Smooth and Enhanced Microelectric Heat Sources in a Rectangular Channel. Journal of Heat Transfer, Vol. 111, pp. 1045-1052, November 1989.	✓
		MONDE, M. et al., Critical Heat Flux in Saturated Forced Convective Boiling on a Heated Disk with Multiple Impinging Jets. Transactions of the ASME, Vol. 113, pp. 722-727, August 1991	✓
		MUDAWAR, I. et al., Direct-Immersion Cooling for High Power Electronic Chips, Intersociety Conference on Thermal Phenomena in Electronic Systems, Four Seasons Hotel, Austin, Texas, February 3-5, 1992.	✓
		MUDAWAR, Prof. Issam, Keynote Address on Thermal Management. International Conference on Thermal, Mechanics and Thermomechanical Phenomena in Electronic Systems, Las Vegas, Nevada, May 23-26, 2000.	✓
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		PENG, X. F. et al., Forced convection and flow boiling heat transfer for liquid flowing through microchannels. Int. J. Heat Mass Transfer, Vol. 36, No. 14, pp. 3421-3427, 1993, Great Britain.	

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		Advances in Thermal Modeling of Electronic Components and Systems, Vol. 2, ASME Press Series, New York, 1990.	✓
		Ravigururajan, T.S., Impact of Channel Geometry on Two-Phase Flow Heat Transfer Characteristics of Refrigerants in Microchannel Heat Exchangers. Journal of Heat Transfer, Vol. 120, pp. 485-491, May 1998.	
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